

# WIDE BAND LOW NOISE AMPLIFIER GaAs MMIC

#### **■** GENERAL DESCRIPTION

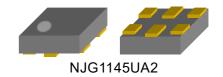
The NJG1145UA2 is a fully matched wide band low noise amplifier GaAs MMIC for terrestrial and satellite applications.

To achieve wide dynamic range, the NJG1145UA2 offers high gain mode and low gain mode. Selecting high gain mode for weak signals, the NJG1145UA2 helps improve receiver sensitivity through high gain and low noise figure. Selecting low gain mode for strong signals, it bypasses LNA circuit to offer higher linearity. In high gain mode, the NJG1145UA2 achieves high gain and high IIP3 across the band.

The ESD protection circuits are integrated into the MMIC. They achieve high ESD protection voltage.

An ultra-small and ultra-thin package of EPFFP6-A2 is adopted.

#### **■ PACKAGE OUTLINE**



#### **■** APPLICATION

Terrestrial and Satellite applications from 90MHz to2150MHz Digital TV, CATV, BS/CS and Set-top box LTE Router, modem and Base Station

#### **■ FEATURES**

Wide operating frequency range 90MHz~2150MHz

■ Low voltage operation2.8V typ.

External components count
 3pcs. (capacitor: 2pcs, inductor: 1pc)

● Small package size EPFFP6-A2 (package size: 1.0mmx1.0mmx0.37mm typ.)

[High gain mode]

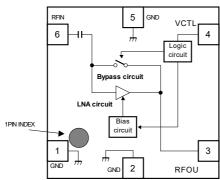
◆ Current consumption
◆ High gain
◆ Low noise figure
20mA typ.
+15.0dB typ.
1.5dB typ.

[Low gain mode]

Low current consumptionGain(Low loss)11μA typ.-1.0dB typ.

#### **■ PIN CONFIGURATION**

(Top View)



#### Pin Connection

- 1. GND
- 2. GND
- 3. RFOUT
- 4. VCTL
- 5. GND
- 6. RFIN

# ■ TRUTH TABLE "H"=V<sub>CTL(H)</sub>"L"=V<sub>CTL(L)</sub>

V <sub>CTL</sub>	LNA ON	Bypass	LNA mode
Н	ON	OFF	High Gain mode
L	OFF	ON	Low Gain mode

Note: Specifications and description listed in this datasheet are subject to change without notice.

### ■ ABSOLUTE MAXIMUM RATINGS

 $T_a=+25$ °C,  $Z_s=Z_l=50$  ohm

		• a	· 20 0, 2s 2	00 0111111
PARAMETER	SYMBOL	CONDITIONS	RATINGS	UNITS
Supply voltage	$V_{DD}$		5.0	V
Control voltage	V <sub>CTL</sub>		5.0	V
Input power	P <sub>IN</sub>	V <sub>DD</sub> =2.8V	+15	dBm
Power dissipation	P <sub>D</sub>	4-layer FR4 PCB with through-hole (101.5x114.5mm), T <sub>j</sub> =150°C	590	mW
Operating temperature	$T_{opr}$		-40~+85	°C
Storage temperature	$T_{stg}$		-55~+150	°C

# ■ ELECTRICAL CHARACTERISTICS1 (DC CHARACTERISTICS)

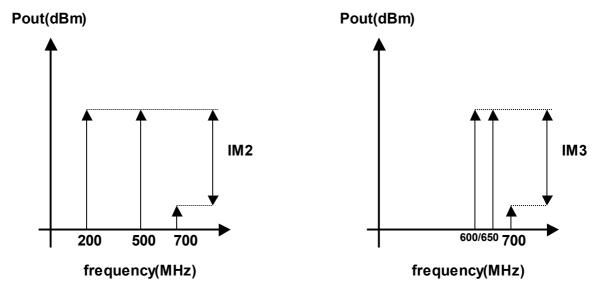
		General conditions: V <sub>DD</sub>	=2.8V, T	<sub>a</sub> =+25°C	$Z_s = Z_l = Z_l$	50 ohm
PARAMETERS	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
Operating voltage	$V_{DD}$		2.3	2.8	3.6	V
Control voltage (High)	$V_{\text{CTL}(H)}$		1.3	1.8	3.6	V
Control voltage (Low)	$V_{\text{CTL}(L)}$		0.0	0.0	0.5	V
Operating current1	$I_{DD1}$	RF OFF, V <sub>CTL</sub> =1.8V	-	20.0	27.0	mA
Operating current2	I <sub>DD2</sub>	RF OFF, V <sub>CTL</sub> =0V	-	11.0	25.0	μΑ
Control current	I <sub>CTL</sub>	RF OFF, V <sub>CTL</sub> =1.8V	-	6.0	10.0	μΑ

# ■ ELECTRICAL CHARACTERISTICS2 (High Gain mode)

Conditions: freq=90~2150MHz, $V_{DD}$ =2.8V, $V_{CTL}$ =1.8V, $T_a$ =+25°C, $Z_s$ = $Z_l$ =50 ohm						
PARAMETERS	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
Small signal gain1	Gain1	Exclude PCB, connector losses*1	12.0	15.0	18.0	dB
Noise figure1	NF1	Exclude PCB, connector losses*2	-	1.5	2.3	dB
Input power 1dB gain compression1	P <sub>-1dB(IN)</sub> 1		-5.0	+0.0	1	dBm
Input 3rd order intercept point1	IIP3_1	f1=freq, f2=freq+100kHz, P <sub>IN</sub> =-26dBm	+2.0	+10.0	1	dBm
2nd order IMD1	IM2_1	f1=200MHz, f2=500MHz, fmeas=700MHz, P <sub>IN</sub> 1=P <sub>IN</sub> 2=-15dBm *3	20.0	28.0	1	dB
3rd order IMD1	IM3_1	f1=600MHz, f2=650MHz, fmeas=700MHz, P <sub>IN</sub> 1=P <sub>IN</sub> 2=-15dBm *3	35.0	45.0	-	dB
Isolation	ISL	S12	-	-19.0	-15.0	dB
RF IN VSWR1	VSWRi1		-	2.2	3.2	-
RF OUT VSWR1	VSWRo1		-	1.5	2.2	-

<sup>\*1</sup> Input & output PCB and connector losses: 0.037dB(90MHz), 0.092dB(620MHz), 0.274dB(2150MHz)

#### \*3 Definitions of IM2 and IM3.

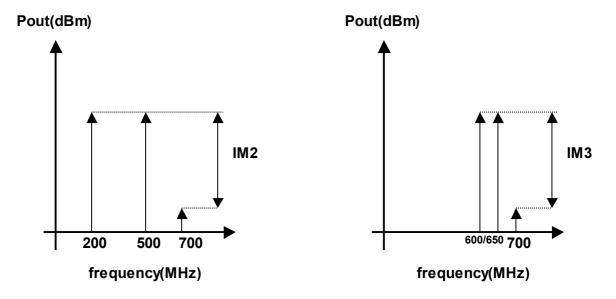


<sup>\*2</sup> Input PCB and connector losses: 0.019dB(90MHz), 0.046dB(620MHz), 0.122dB(2150MHz)

### **■ ELECTRICAL CHARACTERISTICS3** (Low Gain mode)

Conditions: freq=90~2150MHz,  $V_{DD}$ =2.8V,  $V_{CTL}$ = $\frac{0}{V}$ ,  $T_a$ =+25°C,  $Z_s$ = $Z_l$ =50 ohm **SYMBOL** MIN **TYP PARAMETERS CONDITIONS** MAX **UNITS** Exclude PCB, Small signal gain2 Gain2 -6.0 -1.0 dΒ connector losses\*1 Input power at 1dB P-1dB(IN)2 +10.0 +15.0 dBm gain compression2 Input 3rd order f1=freq, f2=freq+100kHz, IIP3 2 +20.0 +30.0 dBm intercept point2 P<sub>IN</sub>=-6dBm f1=200MHz, f2=500MHz 2nd order IMD2 IMD2 2 fmeas=700MHz, 55.0 66.0 dB P<sub>IN</sub>1=P<sub>IN</sub>2=-8dBm \*3 f1=600MHz, f2=650MHz 3rd order IMD2 IMD3 2 fmeas=700MHz, 65.0 75.0 dΒ  $P_{IN}1=P_{IN}2=-8dBm *3$ RF IN VSWR2 VSWRi2 1.5 4.0 RF OUT VSWR2 VSWRo2 1.5 4.0

<sup>\*3</sup> Definitions of IM2 and IM3.



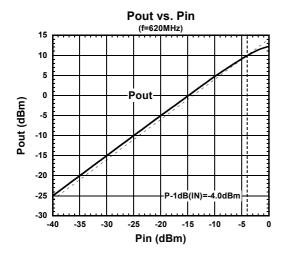
<sup>\*1</sup> Input & output PCB and connector losses: 0.037dB(90MHz), 0.092dB(620MHz), 0.274dB(2150MHz)

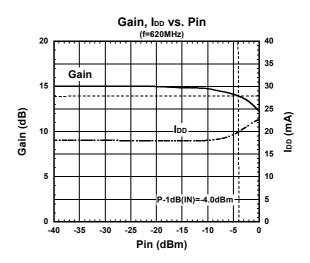
# **■ TERMINAL INFORMATION**

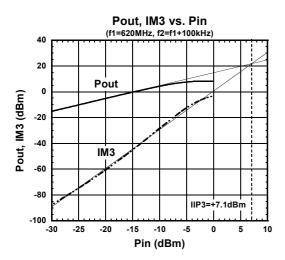
No.	SYMBOL	DESCRIPTION
1	GND	Ground terminal. This terminal should be connected to the ground plane as close as possible for excellent RF performance.
2	GND	Ground terminal. This terminal should be connected to the ground plane as close as possible for excellent RF performance.
3	RFOUT	RF output terminal. This terminal doubles as the drain terminal of the LNA. Please connect this terminal to the power supply(VDD) via inductor(L1).
4	VCTL	Control voltage terminal.
5	GND	Ground terminal. This terminal should be connected to the ground plane as close as possible for excellent RF performance.
6	RFIN	RF input terminal. This IC integrates an input DC blocking capacitor.

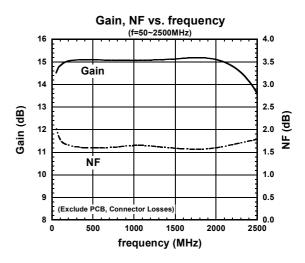
# ■ ELECTRICAL CHARACTERISTICS (High Gain mode)

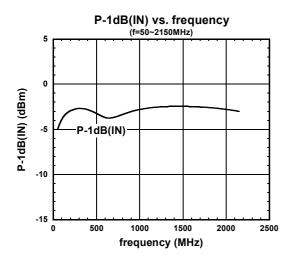
Conditions:  $V_{DD}=2.8V$ ,  $V_{CTL}=1.8V$ ,  $Ta=25^{\circ}C$ ,  $Z_{s}=Z_{l}=50$  ohm, with application circuit

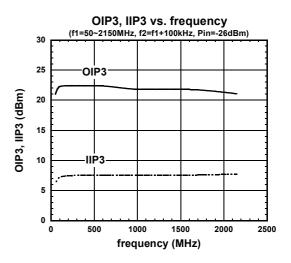






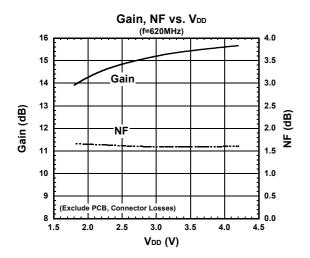


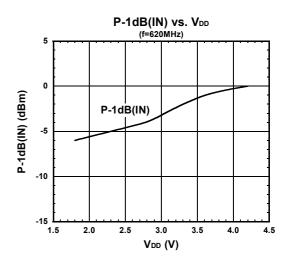


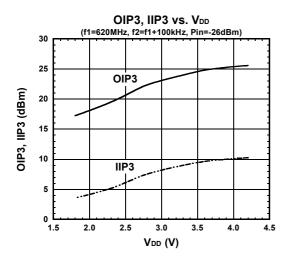


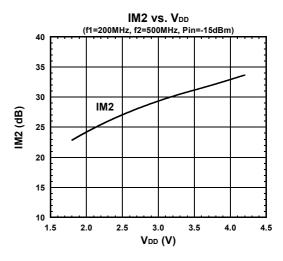
### ■ ELECTRICAL CHARACTERISTICS (High Gain mode)

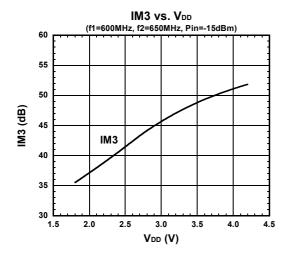
Conditions: V<sub>CTL</sub>=1.8V, Ta=25°C, Z<sub>s</sub>=Z<sub>l</sub>=50 ohm, with application circuit

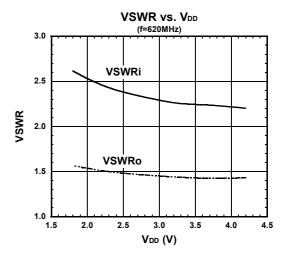






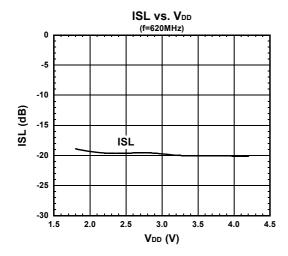


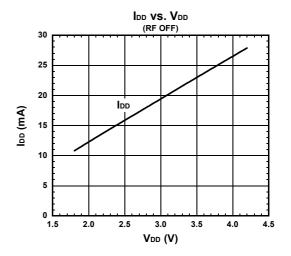




# ■ ELECTRICAL CHARACTERISTICS (High Gain mode)

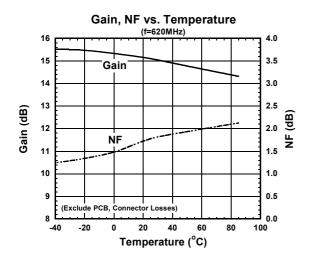
Conditions:  $V_{CTL}=1.8V$ ,  $Ta=25^{\circ}C$ ,  $Z_{s}=Z_{l}=50$  ohm, with application circuit

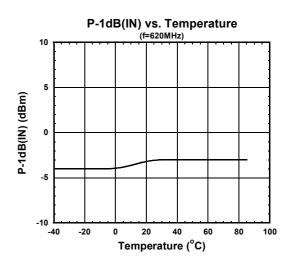


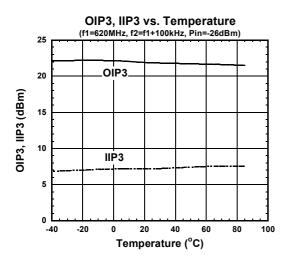


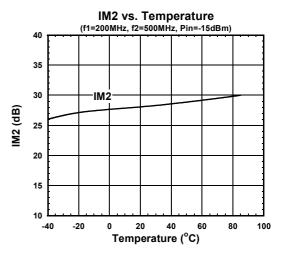
### ■ ELECTRICAL CHARACTERISTICS (High Gain mode)

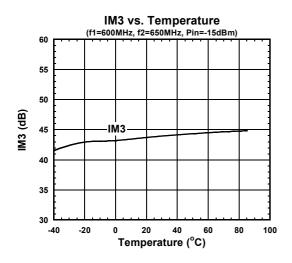
Conditions:  $V_{DD}=2.8V$ ,  $V_{CTL}=1.8V$ ,  $Z_s=Z_l=50$  ohm, with application circuit

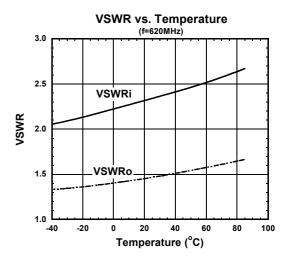






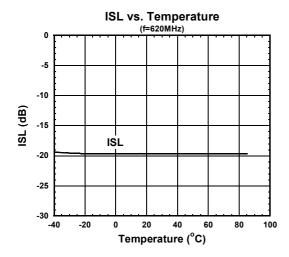


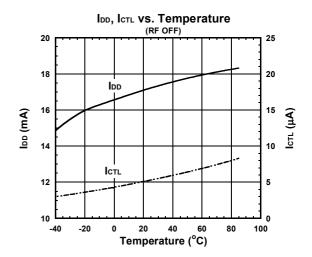


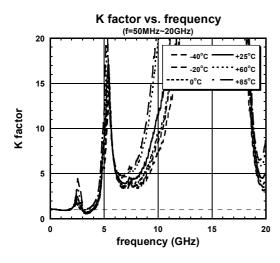


# ■ ELECTRICAL CHARACTERISTICS (High Gain mode)

Conditions:  $V_{DD}$ =2.8V,  $V_{CTL}$ =1.8V,  $Z_s$ = $Z_l$ =50 ohm, with application circuit

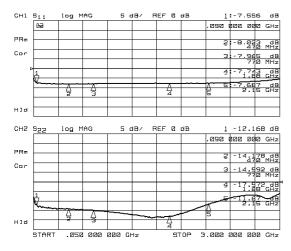




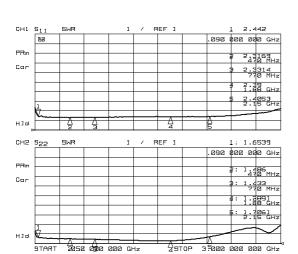


### ■ ELECTRICAL CHARACTERISTICS (Hgih Gain mode)

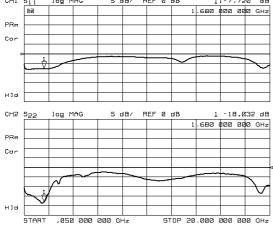
Conditions:  $V_{DD}$ =2.8V,  $V_{CTL}$ =1.8V,  $T_a$ =25°C,  $Z_s$ = $Z_l$ =50 ohm, with application circuit



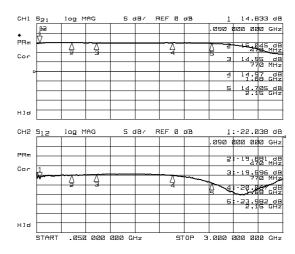
S11, S22 (f=0.05GHz to 3GHz)



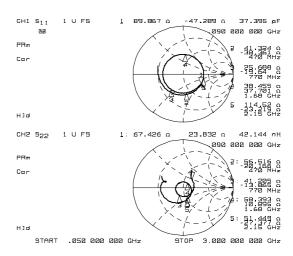
VSWR (f=0.05GHz to 3GHz)



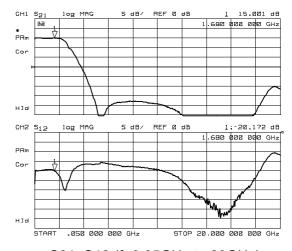
S11, S22 (f=0.05GHz to 20GHz)



S21, S12 (f=0.05GHz to 3GHz)



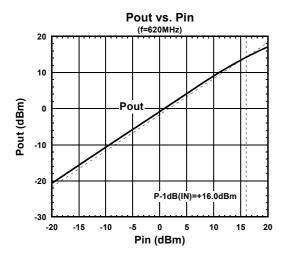
Zin, Zout (f=0.05GHz to 3GHz)

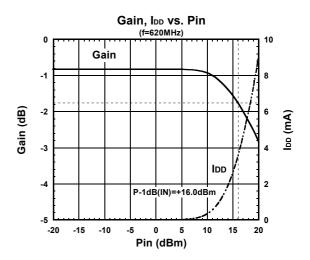


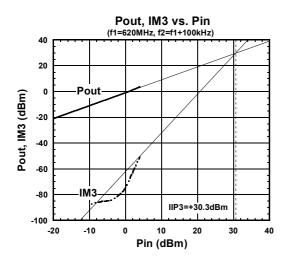
S21, S12 (f=0.05GHz to 20GHz)

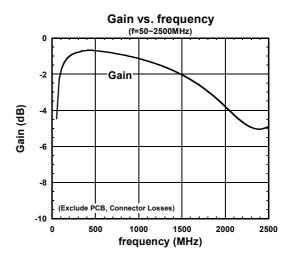
# ■ ELECTRICAL CHARACTERISTICS (Low Gain mode)

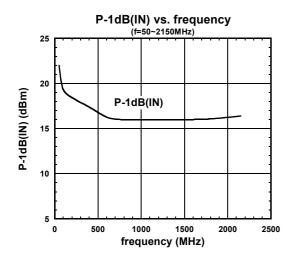
Conditions:  $V_{DD}=2.8V$ ,  $V_{CTL}=0V$ ,  $T_a=25^{\circ}C$ ,  $Z_s=Z_l=50$  ohm, with application circuit

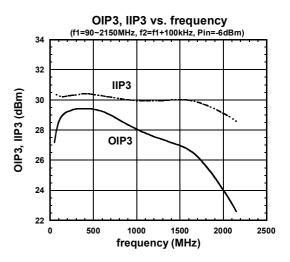






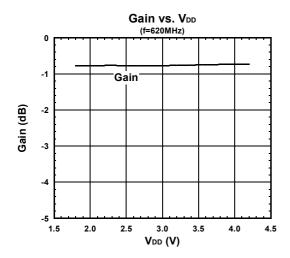


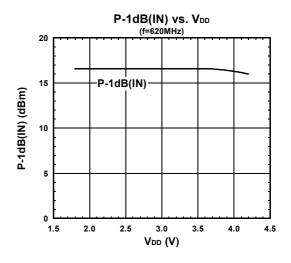


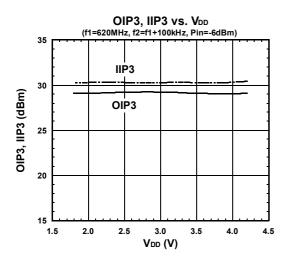


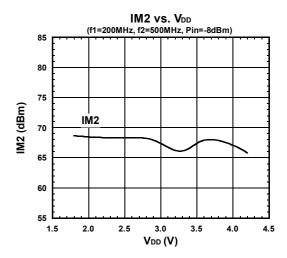
# ■ ELECTRICAL CHARACTERISTICS (Low Gain mode)

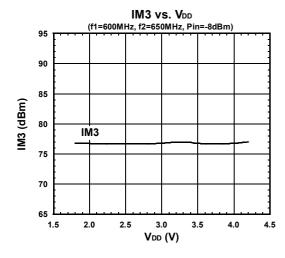
Conditions: V<sub>CTL</sub>=0V, T<sub>a</sub>=25°C, Z<sub>s</sub>=Z<sub>l</sub>=50 ohm, with application circuit

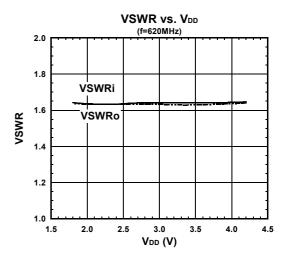






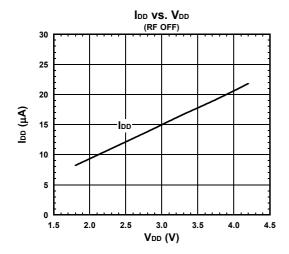






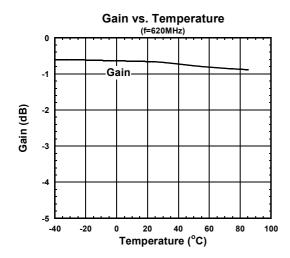
# ■ ELECTRICAL CHARACTERISTICS (Low Gain mode)

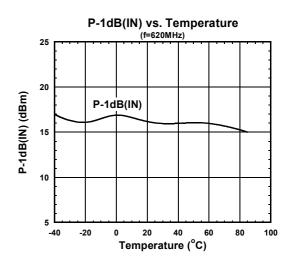
Conditions:  $V_{CTL}=0V$ ,  $T_a=25$ °C,  $Z_s=Z_l=50$  ohm, with application circuit

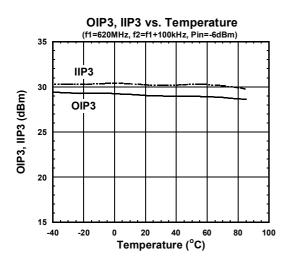


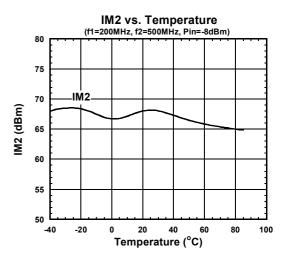
### **■ ELECTRICAL CHARACTERISTICS** (Low Gain mode)

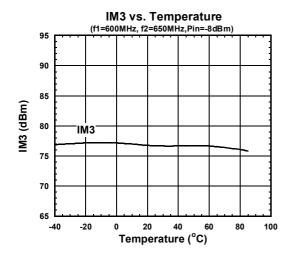
Conditions:  $V_{DD}=2.8V$ ,  $V_{CTL}=0V$ ,  $Z_s=Z_l=50$  ohm, with application circuit

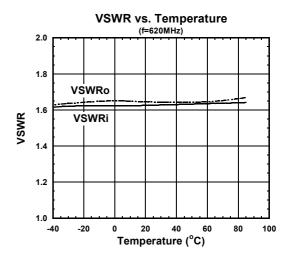






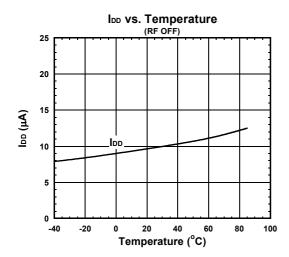


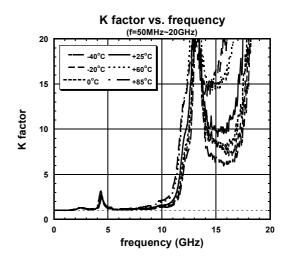


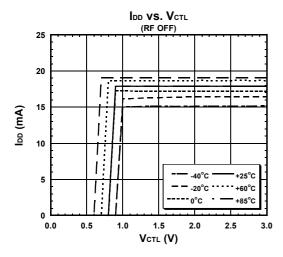


# ■ ELECTRICAL CHARACTERISTICS (Low Gain mode)

Conditions:  $V_{DD}$ =2.8V,  $V_{CTL}$ =0V,  $Z_s$ = $Z_l$ =50 ohm, with application circuit

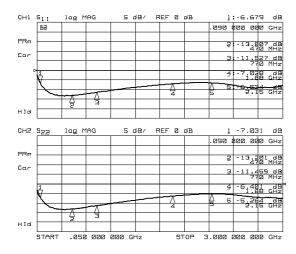




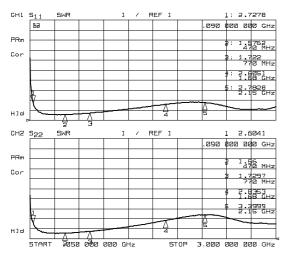


### **■ ELECTRICAL CHARACTERISTICS** (Low Gain mode)

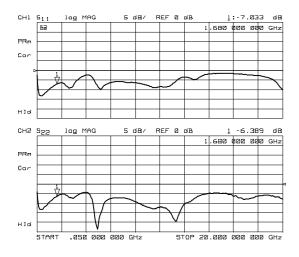
Conditions:  $V_{DD}$ =2.8V,  $V_{CTL}$ =0V,  $T_a$ =25°C,  $Z_s$ = $Z_l$ =50 ohm, with application circuit



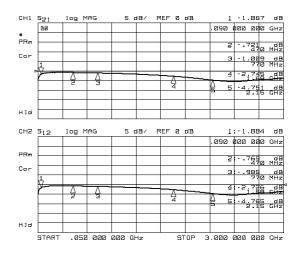
S11, S22 (f= 0.05GHz to 3GHz)



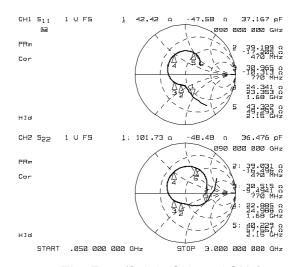
VSWR (f= 0.05GHz to 3GHz)



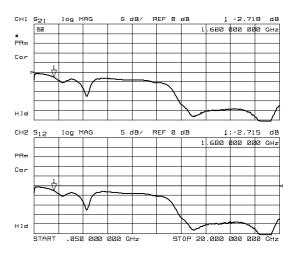
S11, S22 (f= 0.05GHz to 20GHz)



S21, S12 (f= 0.05GHz to 3GHz)

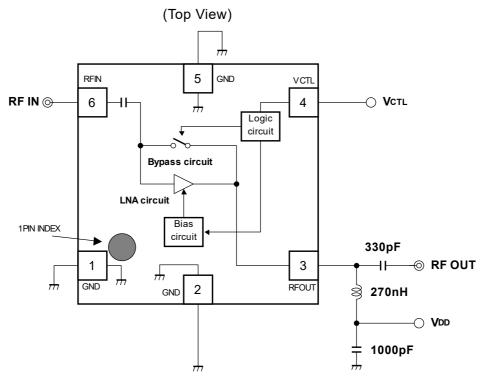


Zin, Zout (f=0.05GHz to 3GHz)



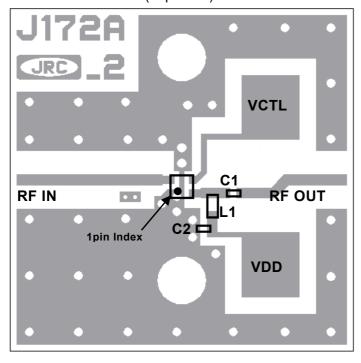
S21, S12 (f= 0.05GHz to 20GHz)

#### **■ APPLICATION CIRCUIT**



#### **■ TEST PCB LAYOUT**

(Top View)



### **■ PARTS LIST**

Parts ID.	Manufacturer
L1	TAIYO-YUDEN
	HK1005 Series
C1, C2	MURATA
01, 02	GRM03 Series

PCB (FR-4):

t=0.2mm

MICROSTRIP LINE WIDTH

=0.40mm ( $Z_0=50$  ohm)

PCB SIZE=14.0mm x 14.0mm

#### **PRECAUTIONS**

- C1 is a coupling and DC blocking capacitor at the output, and C2 is a bypass capacitor.
- L1 is an RF choke. (DC feed inductor)
- In order not to couple with terminal RFIN and RFOUT, please layout ground pattern under the IC.
- All external parts are placed as close as possible to the IC.

#### ■ MEASUREMENT BLOCK DIAGRAM

#### **Measuring instruments**

NF Analyzer : Agilent 8973A Noise Source : Agilent 346A

#### Setting the NF analyzer

Measurement mode form

Device under test : Amplifier

System downconverter: off

Mode setup form

Sideband : LSB

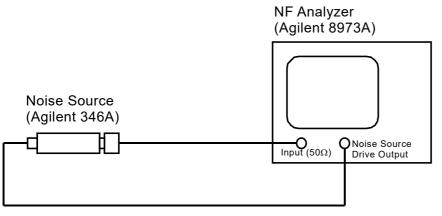
Averages : 16

Average mode : Point

Bandwidth : 4MHz

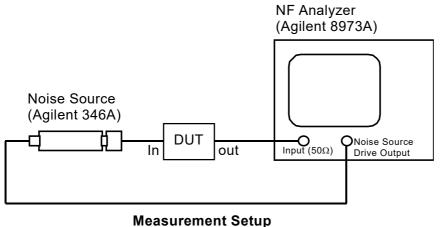
Loss comp : off

Tcold : setting the temperature of noise source (300.0K)



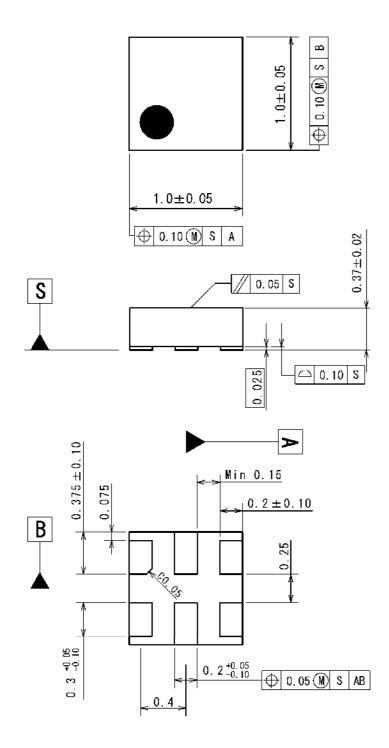
\* Noise source and NF analyzer are connected directly.

#### **Calibration Setup**



\* Noise source and DUT, DUT and NF analyzer are connected directly.

### **■ PACKAGE OUTLINE** (EPFFP6-A2)



Unit :mm :FR-4 Substrate **Terminal Treat** :Au

Molding Material: Epoxy Resin Weight :0.087mg

#### Cautions on using this product

This product contains Gallium-Arsenide (GaAs) which is a harmful material.

- Do NOT eat or put into mouth.
- Do NOT dispose in fire or break up this product.
- Do NOT chemically make gas or powder with this product.
- To waste this product, please obey the relating law of your country.

This product may be damaged with electric static discharge (ESD) or spike voltage. Please handle with care to avoid these damages.

[CAUTION]
The specifications on this databook are only given for information , without any guarantee as regards either mistakes or omissions.
The application circuits in this databook are described only to show representative usages of the product and not intended for the guarantee or permission of any right including the industrial rights.

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  - Aerospace Equipment
  - Equipment Used in the Deep Sea
  - · Power Generator Control Equipment (nuclear, steam, hydraulic, etc.)
  - · Life Maintenance Medical Equipment
  - · Fire Alarms / Intruder Detectors
  - Vehicle Control Equipment (automotive, airplane, railroad, ship, etc.)
  - Various Safety Devices
  - Traffic control system
  - Combustion equipment

In case your company desires to use this product for any applications other than general electronic equipment mentioned above, make sure to contact our company in advance. Note that the important requirements mentioned in this section are not applicable to cases where operation requirements such as application conditions are confirmed by our company in writing after consultation with your company.

- 6. We are making our continuous effort to improve the quality and reliability of our products, but semiconductor products are likely to fail with certain probability. In order to prevent any injury to persons or damages to property resulting from such failure, customers should be careful enough to incorporate safety measures in their design, such as redundancy feature, fire containment feature and fail-safe feature. We do not assume any liability or responsibility for any loss or damage arising from misuse or inappropriate use of the products.
- 7. The products have been designed and tested to function within controlled environmental conditions. Do not use products under conditions that deviate from methods or applications specified in this datasheet. Failure to employ the products in the proper applications can lead to deterioration, destruction or failure of the products. We shall not be responsible for any bodily injury, fires or accident, property damage or any consequential damages resulting from misuse or misapplication of the products.
- 8. Quality Warranty
  - 8-1. Quality Warranty Period
    - In the case of a product purchased through an authorized distributor or directly from us, the warranty period for this product shall be one (1) year after delivery to your company. For defective products that occurred during this period, we will take the quality warranty measures described in section 8-2. However, if there is an agreement on the warranty period in the basic transaction agreement, quality assurance agreement, delivery specifications, etc., it shall be followed.
  - 8-2. Quality Warranty Remedies
    - When it has been proved defective due to manufacturing factors as a result of defect analysis by us, we will either deliver a substitute for the defective product or refund the purchase price of the defective product.
    - Note that such delivery or refund is sole and exclusive remedies to your company for the defective product.
  - 8-3. Remedies after Quality Warranty Period
    - With respect to any defect of this product found after the quality warranty period, the defect will be analyzed by us. On the basis of the defect analysis results, the scope and amounts of damage shall be determined by mutual agreement of both parties. Then we will deal with upper limit in Section 8-2. This provision is not intended to limit any legal rights of your company.
- 9. Anti-radiation design is not implemented in the products described in this document.
- 10. The X-ray exposure can influence functions and characteristics of the products. Confirm the product functions and characteristics in the evaluation stage.
- 11. WLCSP products should be used in light shielded environments. The light exposure can influence functions and characteristics of the products under operation or storage.
- 12. Warning for handling Gallium and Arsenic (GaAs) products (Applying to GaAs MMIC, Photo Reflector). These products use Gallium (Ga) and Arsenic (As) which are specified as poisonous chemicals by law. For the prevention of a hazard, do not burn, destroy, or process chemically to make them as gas or power. When the product is disposed of, please follow the related regulation and do not mix this with general industrial waste or household waste.
- 13. Please contact our sales representatives should you have any questions or comments concerning the products or the technical information.



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